

# HEF4094B

## 8-stage shift-and-store register

Rev. 11 — 29 August 2013

Product data sheet

### 1. General description

The HEF4094B is an 8-stage serial shift register. It has a storage latch associated with each stage for strobing data from the serial input to parallel buffered 3-state outputs QP0 to QP7. The parallel outputs may be connected directly to common bus lines. Data is shifted on positive-going clock transitions. The data in each shift register stage is transferred to the storage register when the strobe (STR) input is HIGH. Data in the storage register appears at the outputs whenever the output enable (OE) signal is HIGH.

Two serial outputs (QS1 and QS2) are available for cascading a number of HEF4094B devices. Serial data is available at QS1 on positive-going clock edges to allow high-speed operation in cascaded systems with a fast clock rise time. The same serial data is available at QS2 on the next negative going clock edge. This is used for cascading HEF4094B devices when the clock has a slow rise time.

It operates over a recommended  $V_{DD}$  power supply range of 3 V to 15 V referenced to  $V_{SS}$  (usually ground). Unused inputs must be connected to  $V_{DD}$ ,  $V_{SS}$ , or another input.

### 2. Features and benefits

- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Complies with JEDEC standard JESD 13-B

### 3. Ordering information

**Table 1. Ordering information**

All types operate from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$ .

Type number	Package		Version
	Name	Description	
HEF4094BP	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
HEF4094BT	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
HEF4094BTS	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
HEF4094BTT	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1



### 4. Functional diagram

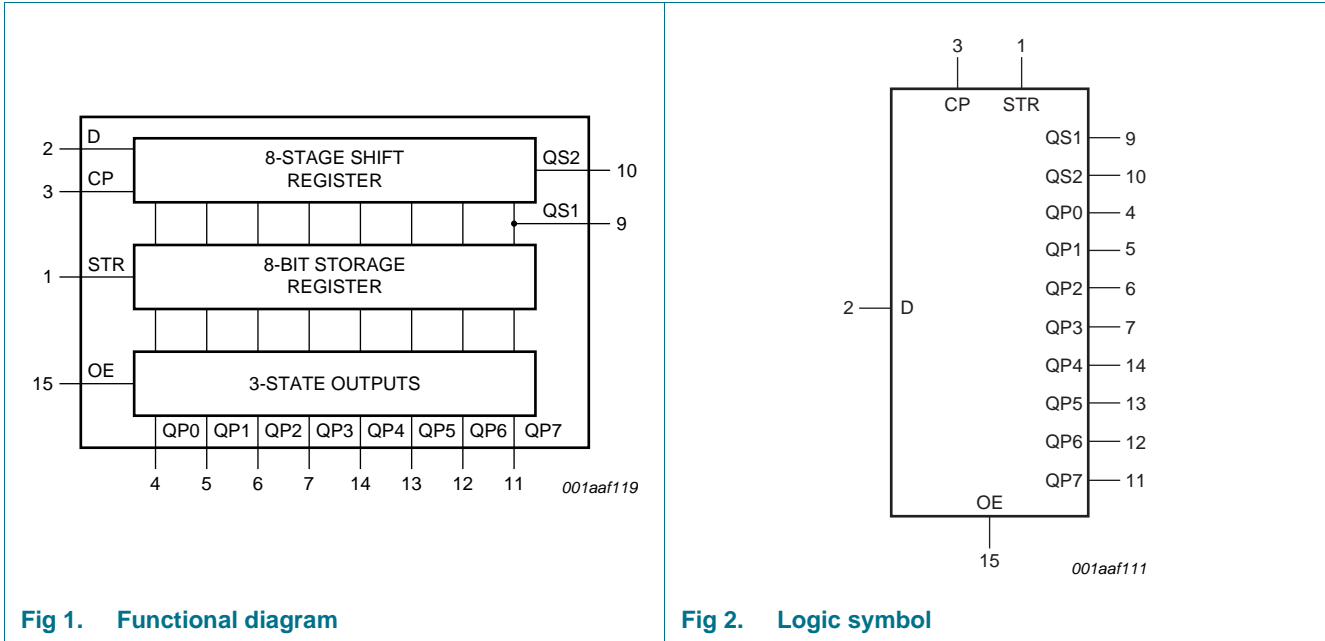


Fig 1. Functional diagram

Fig 2. Logic symbol

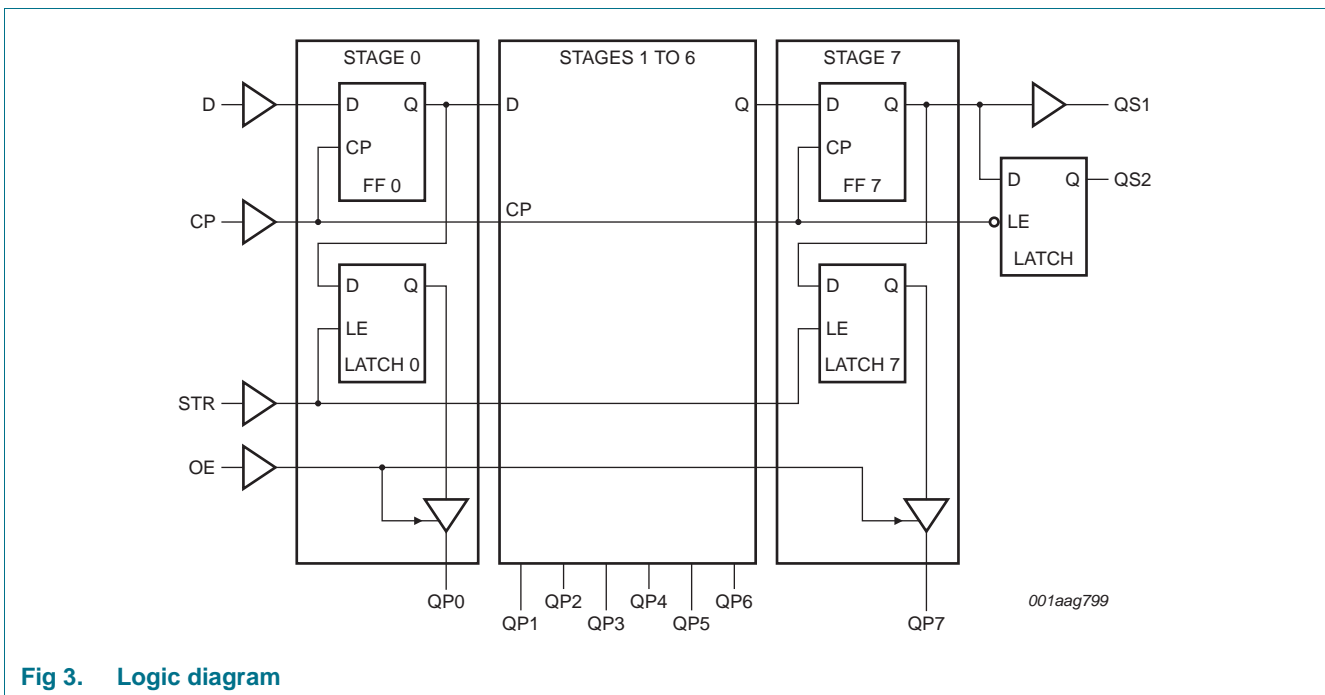
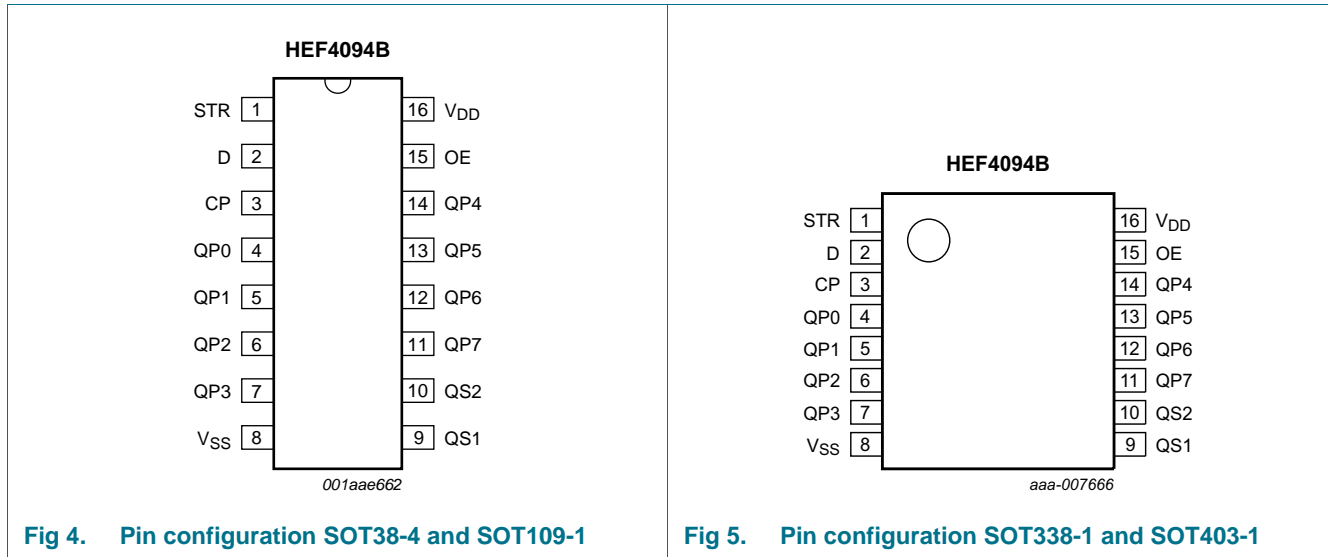


Fig 3. Logic diagram

## 5. Pinning information

### 5.1 Pinning



### 5.2 Pin description

**Table 2. Pin description**

Symbol	Pin	Description
STR	1	strobe input
D	2	data input
CP	3	clock input
QP0 to QP7	4, 5, 6, 7, 14, 13, 12, 11	parallel output
V <sub>SS</sub>	8	ground supply voltage
QS1	9	serial output
QS2	10	serial output
OE	15	output enable input
V <sub>DD</sub>	16	supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Inputs				Parallel outputs		Serial outputs	
CP	OE	STR	D	QP0	QPn	QS1	QS2
↑	L	X	X	Z	Z	Q6S	NC
↓	L	X	X	Z	Z	NC	Q7S
↑	H	L	X	NC	NC	Q6S	NC
↑	H	H	L	L	QPn - 1	Q6S	NC
↑	H	H	H	H	QPn - 1	Q6S	NC
↓	H	H	H	NC	NC	NC	Q7S

- [1] At the positive clock edge, the information in the 7th register stage is transferred to the 8th register stage and the QSn outputs.  
 H = HIGH voltage level; L = LOW voltage level; X = don't care;  
 ↑ = positive-going transition; ↓ = negative-going transition;  
 Z = HIGH-impedance OFF-state; NC = no change;  
 Q6S = the data in register stage 6 before the LOW to HIGH clock transition;  
 Q7S = the data in register stage 7 before the HIGH to LOW clock transition.

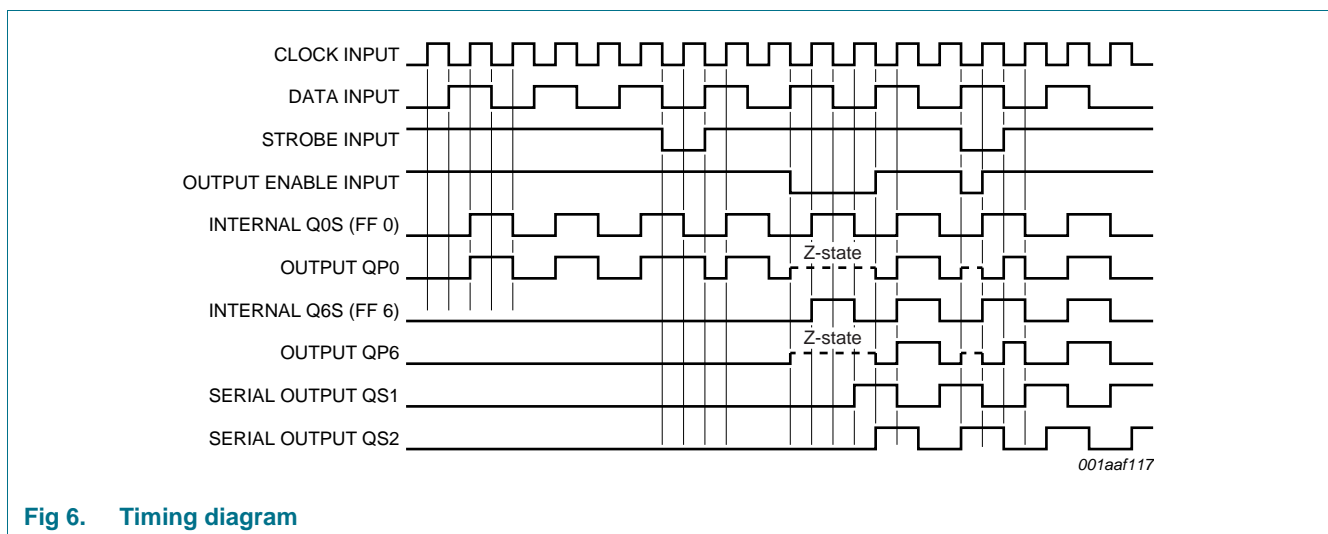


Fig 6. Timing diagram

## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to  $V_{SS} = 0$  V (ground).

Symbol	Parameter	Conditions	Min	Max	Unit	
$V_{DD}$	supply voltage		-0.5	+18	V	
$I_{IK}$	input clamping current	$V_I < -0.5$ V or $V_I > V_{DD} + 0.5$ V	-	$\pm 10$	mA	
$V_I$	input voltage		-0.5	$V_{DD} + 0.5$	V	
$I_{OK}$	output clamping current	$V_O < -0.5$ V or $V_O > V_{DD} + 0.5$ V	-	$\pm 10$	mA	
$I_{I/O}$	input/output current		-	$\pm 10$	mA	
$I_{DD}$	supply current		-	50	mA	
$T_{stg}$	storage temperature		-65	+150	°C	
$T_{amb}$	ambient temperature		-40	+125	°C	
$P_{tot}$	total power dissipation	DIP16	<a href="#">[1]</a>	-	750	mW
		SO16, SSOP16 and TSSOP16	<a href="#">[2]</a>	-	500	mW
$P$	power dissipation	per output	-	100	mW	

[1] For DIP16 packages: above  $T_{amb} = 70$  °C,  $P_{tot}$  derates linearly with 12 mW/K.

[2] For SO16 package:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.

For (T)SSOP16 package:  $P_{tot}$  derates linearly with 5.5 mW/K above 60 °C.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DD}$	supply voltage		3	-	15	V
$V_I$	input voltage		0	-	$V_{DD}$	V
$T_{amb}$	ambient temperature	in free air	-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{DD} = 5$ V	-	-	3.75	$\mu\text{s/V}$
		$V_{DD} = 10$ V	-	-	0.5	$\mu\text{s/V}$
		$V_{DD} = 15$ V	-	-	0.08	$\mu\text{s/V}$

## 9. Static characteristics

**Table 6. Static characteristics**

$V_{SS} = 0\text{ V}$ ;  $V_I = V_{SS}$  or  $V_{DD}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	$T_{amb} = -40\text{ °C}$		$T_{amb} = +25\text{ °C}$		$T_{amb} = +85\text{ °C}$		$T_{amb} = +125\text{ °C}$		Unit
				Min	Max	Min	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	3.5	-	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	11.0	-	V
$V_{IL}$	LOW-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	1.5	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	-	4.0	V
$V_{OH}$	HIGH-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	4.95	-	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	14.95	-	V
$V_{OL}$	LOW-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	0.05	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	-	0.05	V
$I_{OH}$	HIGH-level output current	$V_O = 2.5\text{ V}$	5 V	-	-1.7	-	-1.4	-	-1.1	-	-1.1	mA
		$V_O = 4.6\text{ V}$	5 V	-	-0.64	-	-0.5	-	-0.36	-	-0.36	mA
		$V_O = 9.5\text{ V}$	10 V	-	-1.6	-	-1.3	-	-0.9	-	-0.9	mA
		$V_O = 13.5\text{ V}$	15 V	-	-4.2	-	-3.4	-	-2.4	-	-2.4	mA
$I_{OL}$	LOW-level output current	$V_O = 0.4\text{ V}$	5 V	0.64	-	0.5	-	0.36	-	0.36	-	mA
		$V_O = 0.5\text{ V}$	10 V	1.6	-	1.3	-	0.9	-	0.9	-	mA
		$V_O = 1.5\text{ V}$	15 V	4.2	-	3.4	-	2.4	-	2.4	-	mA
$I_{OZ}$	OFF-state output current	QPn output is HIGH; $V_O = 15\text{ V}$	15 V	-	0.4	-	0.4	-	12	-	12	$\mu\text{A}$
$I_I$	input leakage current		15 V	-	$\pm 0.1$	-	$\pm 0.1$	-	$\pm 1.0$	-	$\pm 1.0$	$\mu\text{A}$
$I_{DD}$	supply current	all valid input combinations; $I_O = 0\text{ A}$	5 V	-	5	-	5	-	150	-	150	$\mu\text{A}$
			10 V	-	10	-	10	-	300	-	300	$\mu\text{A}$
			15 V	-	20	-	20	-	600	-	600	$\mu\text{A}$
$C_I$	input capacitance			-	-	-	7.5	-	-	-	pF	

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

$V_{SS} = 0\text{ V}$ ;  $T_{amb} = 25\text{ °C}$ ; for test circuit see [Figure 11](#); unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	Extrapolation formula	Min	Typ	Max	Unit
$t_{PHL}$	HIGH to LOW propagation delay	CP to QS1; see <a href="#">Figure 7</a>	5 V	<sup>[1]</sup> $108\text{ ns} + (0.55\text{ ns/pF})C_L$	-	135	270	ns
			10 V	$54\text{ ns} + (0.23\text{ ns/pF})C_L$	-	65	130	ns
			15 V	$42\text{ ns} + (0.16\text{ ns/pF})C_L$	-	50	100	ns
		CP to QS2; see <a href="#">Figure 7</a>	5 V	$78\text{ ns} + (0.55\text{ ns/pF})C_L$	-	105	210	ns
			10 V	$39\text{ ns} + (0.23\text{ ns/pF})C_L$	-	50	100	ns
			15 V	$32\text{ ns} + (0.16\text{ ns/pF})C_L$	-	40	80	ns
		CP to QPn; see <a href="#">Figure 7</a>	5 V	$138\text{ ns} + (0.55\text{ ns/pF})C_L$	-	165	330	ns
			10 V	$64\text{ ns} + (0.23\text{ ns/pF})C_L$	-	75	150	ns
			15 V	$47\text{ ns} + (0.16\text{ ns/pF})C_L$	-	55	110	ns
		STR to QPn; see <a href="#">Figure 8</a>	5 V	$83\text{ ns} + (0.55\text{ ns/pF})C_L$	-	110	220	ns
			10 V	$39\text{ ns} + (0.23\text{ ns/pF})C_L$	-	50	100	ns
			15 V	$27\text{ ns} + (0.16\text{ ns/pF})C_L$	-	35	70	ns
$t_{PLH}$	LOW to HIGH propagation delay,	CP to QS1; see <a href="#">Figure 7</a>	5 V	<sup>[1]</sup> $78\text{ ns} + (0.55\text{ ns/pF})C_L$	-	105	210	ns
			10 V	$39\text{ ns} + (0.23\text{ ns/pF})C_L$	-	50	100	ns
			15 V	$32\text{ ns} + (0.16\text{ ns/pF})C_L$	-	40	80	ns
		CP to QS2; see <a href="#">Figure 7</a>	5 V	$78\text{ ns} + (0.55\text{ ns/pF})C_L$	-	105	210	ns
			10 V	$39\text{ ns} + (0.23\text{ ns/pF})C_L$	-	50	100	ns
			15 V	$32\text{ ns} + (0.16\text{ ns/pF})C_L$	-	40	80	ns
		CP to QPn; see <a href="#">Figure 7</a>	5 V	$123\text{ ns} + (0.55\text{ ns/pF})C_L$	-	150	300	ns
			10 V	$59\text{ ns} + (0.23\text{ ns/pF})C_L$	-	70	140	ns
			15 V	$47\text{ ns} + (0.16\text{ ns/pF})C_L$	-	55	110	ns
		STR to QPn; see <a href="#">Figure 8</a>	5 V	$73\text{ ns} + (0.55\text{ ns/pF})C_L$	-	100	200	ns
			10 V	$34\text{ ns} + (0.23\text{ ns/pF})C_L$	-	45	90	ns
			15 V	$27\text{ ns} + (0.16\text{ ns/pF})C_L$	-	35	70	ns
$t_t$	transition time	5 V	<sup>[1]</sup> $10\text{ ns} + (1.00\text{ ns/pF})C_L$	-	60	120	ns	
		10 V	$9\text{ ns} + (0.42\text{ ns/pF})C_L$	-	30	60	ns	
		15 V	$6\text{ ns} + (0.28\text{ ns/pF})C_L$	-	20	40	ns	
$t_{PZH}$	OFF-state to HIGH propagation delay	OE to QPn; see <a href="#">Figure 9</a>	5 V	-	-	40	80	ns
		10 V	-	-	25	50	ns	
		15 V	-	-	20	40	ns	
$t_{PZL}$	OFF-state to LOW propagation delay	OE to QPn; see <a href="#">Figure 9</a>	5 V	-	-	40	80	ns
		10 V	-	-	25	50	ns	
		15 V	-	-	20	40	ns	
$t_{PHZ}$	HIGH to OFF-state propagation delay	OE to QPn; see <a href="#">Figure 9</a>	5 V	-	-	75	150	ns
		10 V	-	-	40	80	ns	
		15 V	-	-	30	60	ns	

**Table 7. Dynamic characteristics ...continued**

$V_{SS} = 0\text{ V}$ ;  $T_{amb} = 25\text{ °C}$ ; for test circuit see [Figure 11](#); unless otherwise specified.

Symbol	Parameter	Conditions	V <sub>DD</sub>	Extrapolation formula	Min	Typ	Max	Unit
t <sub>PLZ</sub>	LOW to OFF-state propagation delay	OE to QPn; see <a href="#">Figure 9</a>	5 V		-	80	160	ns
			10 V		-	40	80	ns
			15 V		-	30	60	ns
t <sub>su</sub>	set-up time	D to CP; see <a href="#">Figure 10</a>	5 V		60	30	-	ns
			10 V		20	10	-	ns
			15 V		15	5	-	ns
t <sub>h</sub>	hold time	D to CP; see <a href="#">Figure 10</a>	5 V		+5	-15	-	ns
			10 V		20	5	-	ns
			15 V		20	5	-	ns
t <sub>w</sub>	pulse width	minimum LOW clock pulse; see <a href="#">Figure 7</a>	5 V		60	30	-	ns
			10 V		30	15	-	ns
			15 V		24	12	-	ns
		minimum HIGH strobe pulse; see <a href="#">Figure 8</a>	5 V		40	20	-	ns
			10 V		30	15	-	ns
			15 V		24	12	-	ns
f <sub>max</sub>	maximum frequency	see <a href="#">Figure 7</a>	5 V		5	10	-	MHz
			10 V		11	22	-	MHz
			15 V		14	28	-	MHz

[1] The typical values of the propagation delay and transition times are calculated from the extrapolation formulas shown (C<sub>L</sub> in pF).

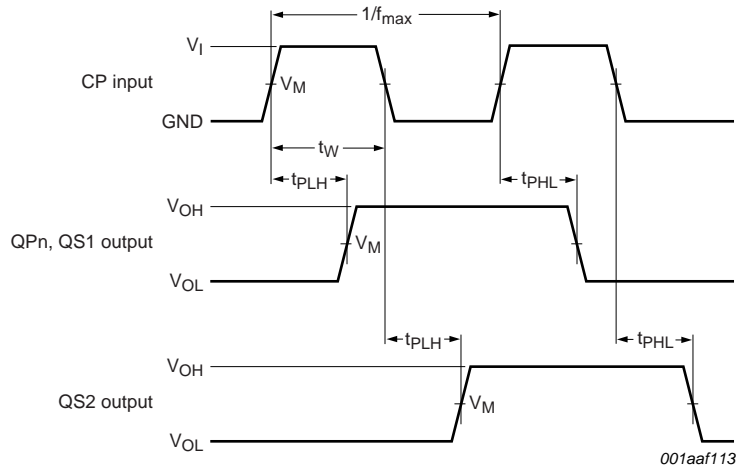
**Table 8. Dynamic power dissipation**

$V_{SS} = 0\text{ V}$ ;  $t_r = t_f \leq 20\text{ ns}$ ;  $T_{amb} = 25\text{ °C}$ .

Symbol	Parameter	V <sub>DD</sub>	Typical formula for P <sub>D</sub> (μW)	where:
P <sub>D</sub>	dynamic power dissipation	5 V	$P_D = 2100 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	f <sub>i</sub> = input frequency in MHz,
		10 V	$P_D = 9700 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	f <sub>o</sub> = output frequency in MHz,
		15 V	$P_D = 26000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	C <sub>L</sub> = output load capacitance in pF,
				V <sub>DD</sub> = supply voltage in V,
				Σ(f <sub>o</sub> × C <sub>L</sub> ) = sum of the outputs.



11. Waveforms



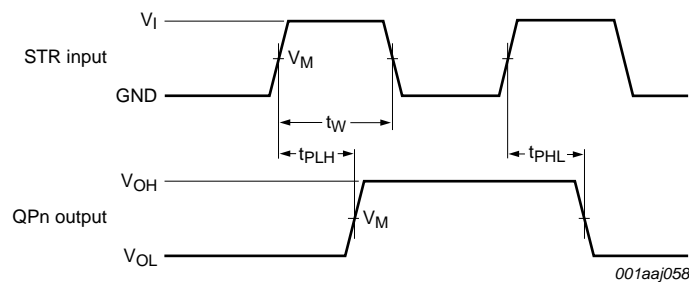
Measurement points are given in [Table 9](#).

Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 7. Clock to outputs propagation delays, and clock pulse width and maximum frequency**

**Table 9. Measurement points**

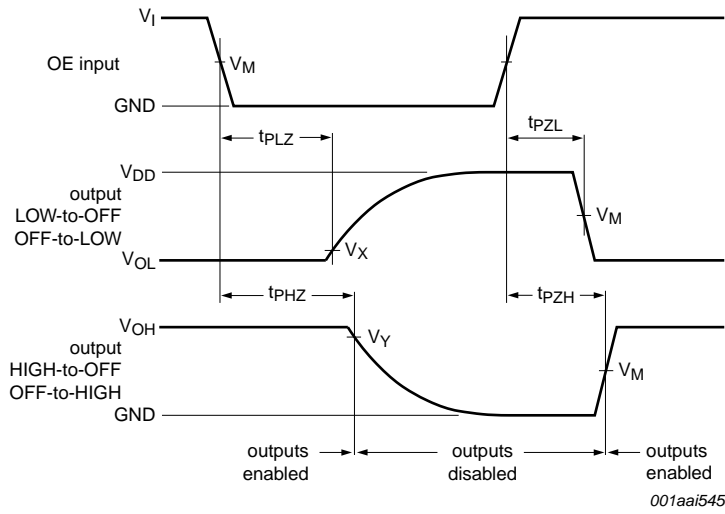
Supply voltage	Input	Output		
$V_{DD}$	$V_M$	$V_M$	$V_X$	$V_Y$
5 V to 15 V	$0.5V_{DD}$	$0.5V_{DD}$	$0.1V_{DD}$	$0.9V_{DD}$



Measurement points are given in [Table 9](#).

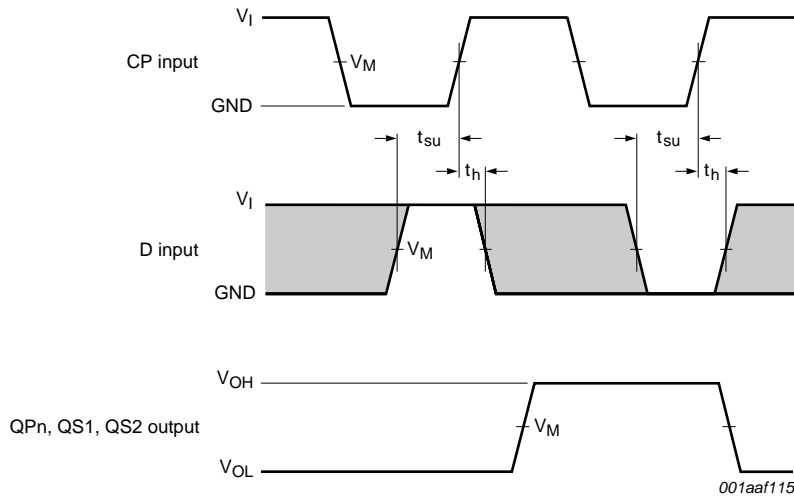
Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 8. Strobe to output propagation delays, and strobe pulse width, set up and hold times**



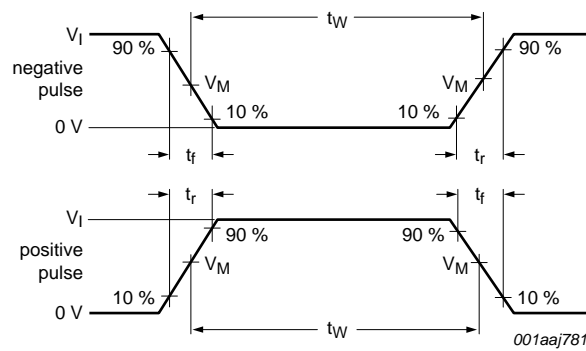
Measurement points are given in [Table 9](#).  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 9. 3-state output enable and disable times for OE input**

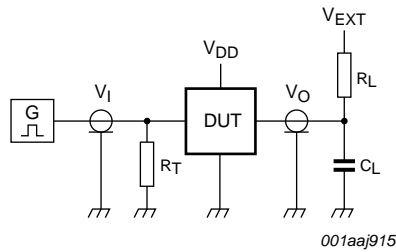


Measurement points are given in [Table 9](#).  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 10. Data input data set up and hold times**



a. Input waveform



b. Test circuit

Test data is given in [Table 10](#).

Definitions for test circuit:

DUT = Device Under Test.

$C_L$  = load capacitance including jig and probe capacitance.

$R_L$  = load resistance.

$R_T$  = termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

Fig 11. Test circuit

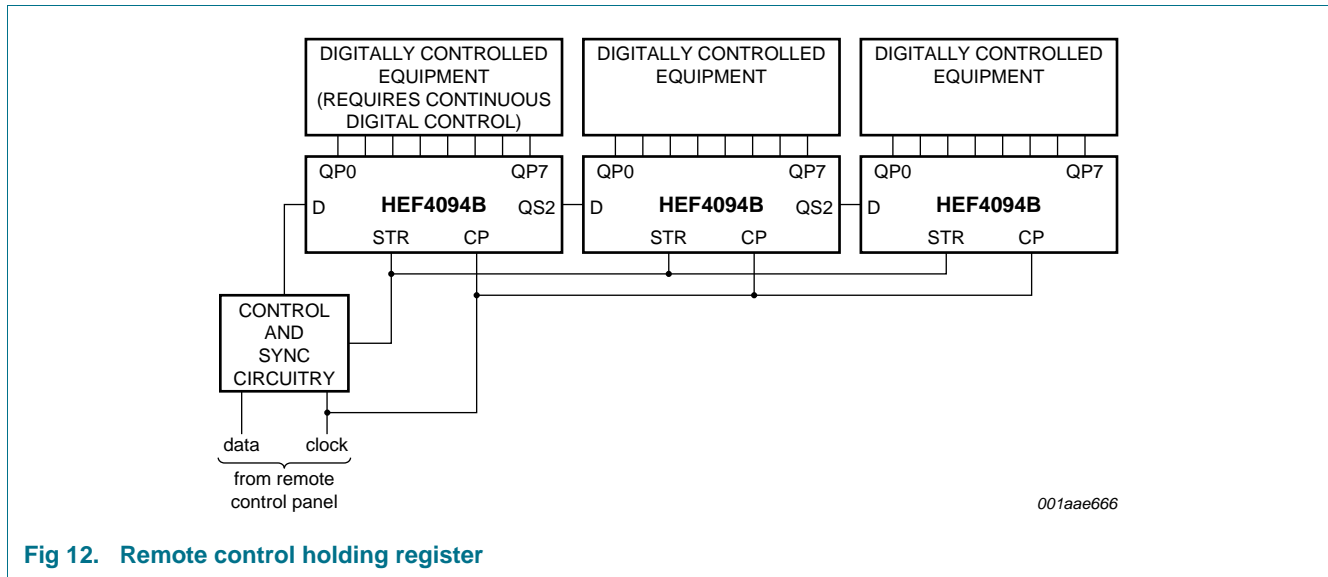
Table 10. Test data

Supply voltage	Input		$V_{EXT}$			Load	
$V_{DD}$	$V_I$	$t_r, t_f$	$t_{PHL}, t_{PLH}$	$t_{PHZ}, t_{PZH}$	$t_{PLZ}, t_{PZL}$	$C_L$	$R_L$
5 V to 15 V	$V_{SS}$ or $V_{DD}$	$\leq 20$ ns	open	$V_{SS}$	$V_{DD}$	50 pF	1 k $\Omega$

## 12. Application information

Some examples of applications for the HEF4094B are:

- Serial-to-parallel data conversion
- Remote control holding register



**Fig 12. Remote control holding register**

13. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4

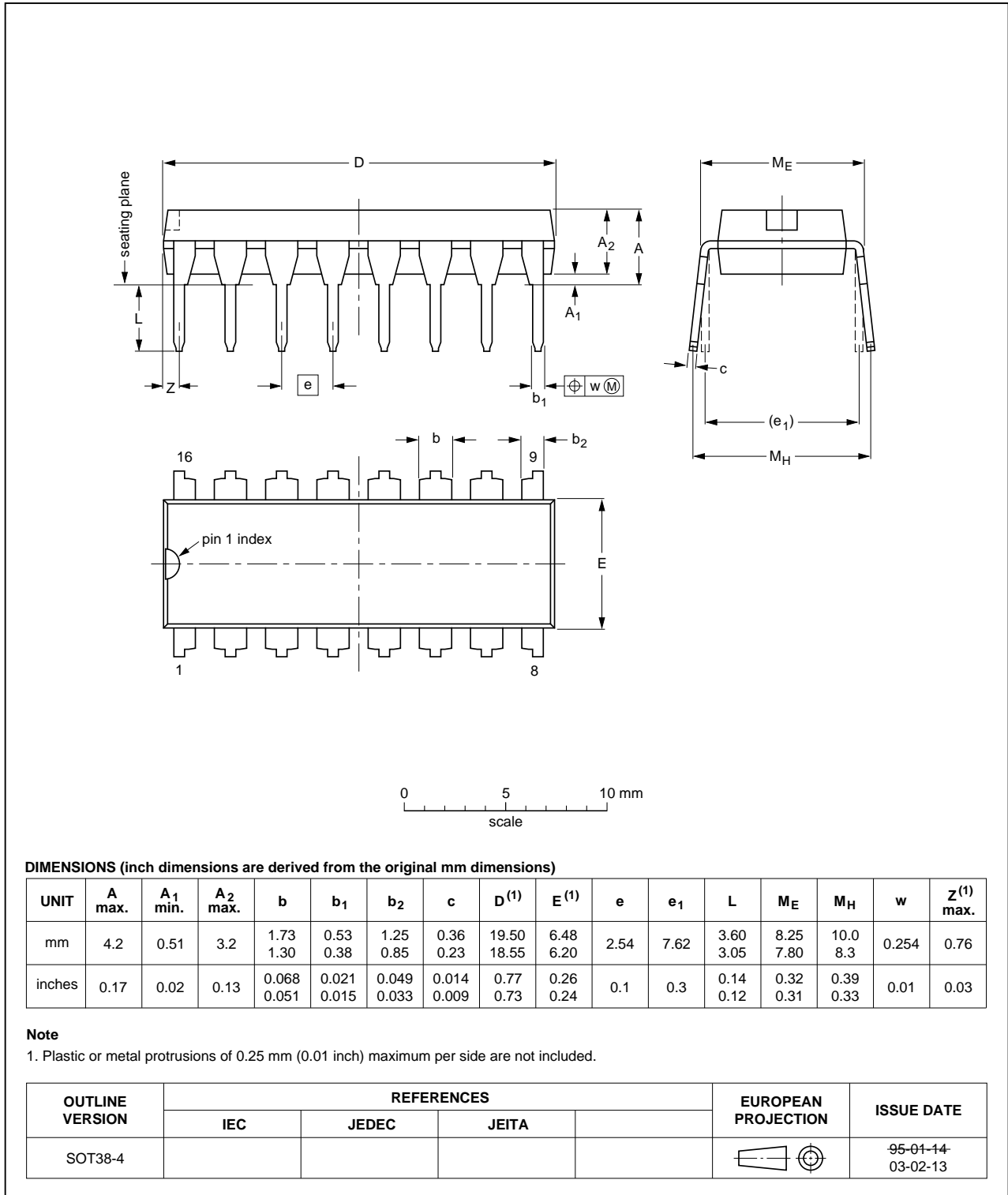


Fig 13. Package outline SOT38-4 (DIP16)

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

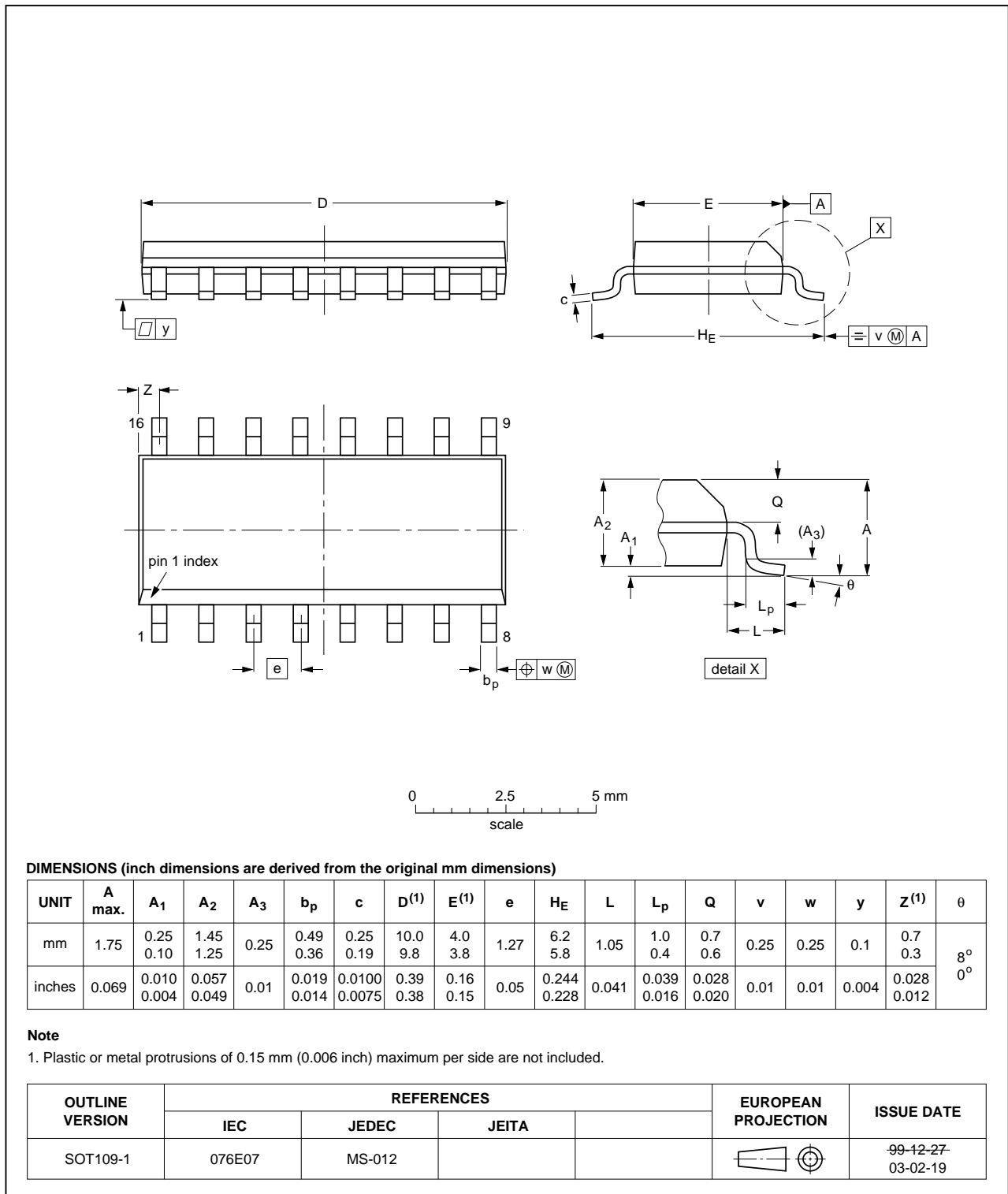


Fig 14. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

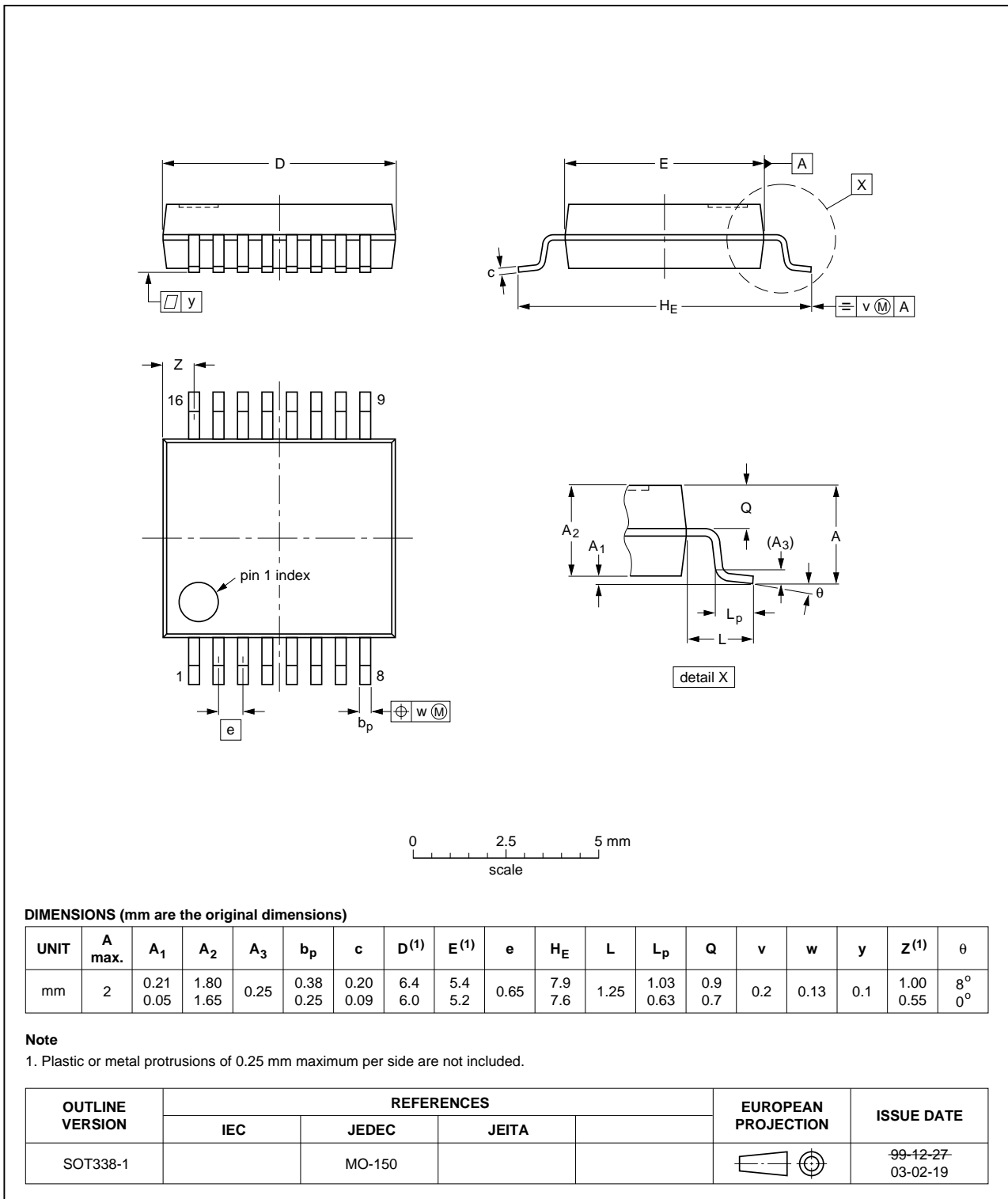


Fig 15. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

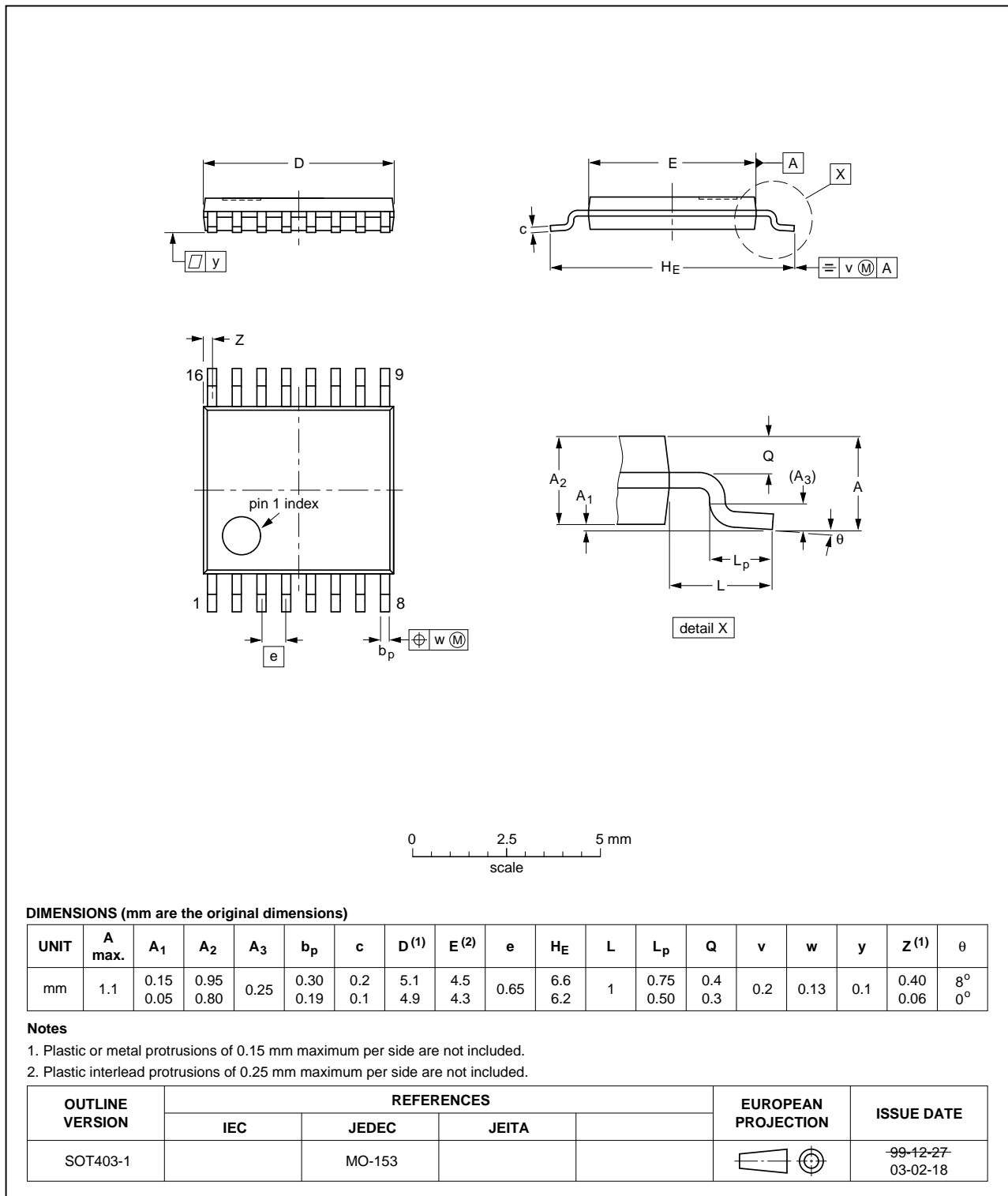


Fig 16. Package outline SOT403-1 (TSSOP16)



## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4094B v.11	20130829	Product data sheet	-	HEF4094B v.10
Modifications:	<ul style="list-style-type: none"> <li>• <a href="#">Table 4</a>: Table note corrected (errata).</li> </ul>			
HEF4094B v.10	20130625	Product data sheet	-	HEF4094B v.9
Modifications:	<ul style="list-style-type: none"> <li>• added type number HEF4094BTT.</li> </ul>			
HEF4094B v.9	20111116	Product data sheet	-	HEF4094B v.8
Modifications:	<ul style="list-style-type: none"> <li>• <a href="#">Table 6</a>: I<sub>OH</sub> minimum values changed to maximum</li> </ul>			
HEF4094B v.8	20100402	Product data sheet	-	HEF4094B v.7
HEF4094B v.7	20091216	Product data sheet	-	HEF4094B v.6
HEF4094B v.6	20091103	Product data sheet	-	HEF4094B v.5
HEF4094B v.5	20090728	Product data sheet	-	HEF4094B v.4
HEF4094B v.4	20081030	Product data sheet	-	HEF4094B_CNV v.3
HEF4094B_CNV v.3	19950101	Product specification	-	HEF4094B_CNV v.2
HEF4094B_CNV v.2	19950101	Product specification	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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